



Re Patent Application of:

Krishna Seshan et al.

WIRE-BOND PROCESS FLOW FOR COPPER METAL-SIX, STRUCTURES ACHIEVED

THEREBY, AND TESTING METHOD

Attorney Docket No.: 884.659US1

PATENT APPLICATION TRANSMITTAL

BOX PATENT APPLICATION

Commissioner for Patents Washington, D.C. 20231

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Utility Patent Application under 37 CFR § 1.53(b) comprising:

- Specification (26 pgs, including claims numbered 1 through 23 and a 1 page Abstract).
- Formal Drawing(s) ($\underline{4}$ sheets).
- Signed Combined Declaration and Power of Attorney (8 pgs).
- Check in the amount of \$794.00 to pay the filing fee.

Assignment of the invention to Intel Corporation (4 pgs) and Recordation Form Cover Sheet.

Check in the amount of \$40.00 to pay the Assignment recording fee.

The filing fee has been calculated below as follows:

	No. Filed	No. Extra	Rate	Fee
TOTAL CLAIMS	23 - 20 =	3	x 18 =	\$54.00
INDEPENDENT CLAIMS	3 - 3 =	0	x 84 =	\$0.00
MULTIPLE DEPENDENT CLAIMS PRESENTED				\$0.00
BASIC FEE				\$740.00
TOTAL				\$794.00

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